

C1206X103F3GECTU

Aliases (C1206X103F3GEC7800)

ESD SMD Comm COG, Ceramic, 0.01 uF, 1%, 25 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 1206, 1.5 mm



Click [here](#) for the 3D model.

General Information

Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	20 mg
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	0.01 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	1%
Voltage DC	25 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOHms

Dimensions

Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
T	0.9mm +/-0.20mm
S	1.5mm MIN
B	0.6mm +/-0.25mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

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